

Notice of References Cited

Application/Control No.

09/942,038

Applicant(s)/Patent Under

Reexamination

MORI ET AL.

Examiner

Yennhu B. Huynh

Art Unit

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2001/0023977A1	09-2001	Tsuzumitani et al.	257/532
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Tsunemine et al., "A manufacturable Integration Technology of Sputter BST Capacitor With a Newly Proposed Thick Pt. Electrode", IEEE, 1998, pp. 30.3.1-30.3.4.
	V	Sun et al.,, "Effect of Bottom Electrode Materials On The Electrical and Reliability Charactistics of (Ba,Sr)TiO ₃ Capacitors", IEEE, 2977, pp. 10.3.1-10.3.4.
	W	
	X	

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 Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.